

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In the application of: Eldridge et al.

Application No.: Unknown

Filing Date: December 27, 2001

For: PROBE CARD ASSEMBLY AND KIT,  
AND METHODS OF USING SAME

Examiner: Unknown

Group Art Unit: Unknown

PRELIMINARY AMENDMENT

Box: New Application  
Assistant Commissioner for Patents  
Washington, D.C. 20231

3 / Prel. amdt.  
B  
E. Vullis  
8-26-02

Dear Sir:

Prior to examination of the above-identified patent application (which is filed herewith),  
please amend the application as follows:

In The Claims

Please cancel claim 1 without prejudice.

Please add new claims 43-57 as follows:

43. (New) A tested semiconductor device produced by a process comprising the steps of:

providing a wafer having a plurality of semiconductor devices thereon, each of said  
semiconductor devices including a plurality of electrical contact pads;

providing a probe card assembly, said probe assembly including a probe card having a  
plurality of electrical contacts, a probe substrate having a plurality of elongate, resilient probe  
elements, and a compliant interconnection structure electrically connecting said ones of said  
electrical contacts with corresponding ones of said probe elements;

contacting said wafer and said probe card assembly such that ones of said electrical  
contact pads of said semiconductor devices are in electrical contact with ones of said probe  
elements; and

testing said semiconductor devices.